

Patent Abstracts of Japan

PUBLICATION NUMBER

03185742

PUBLICATION DATE

13-08-91

APPLICATION DATE

14-12-89

APPLICATION NUMBER

01325121

APPLICANT: NEC CORP;

INVENTOR: KAMI SUKEYUKI;

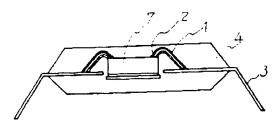
INT.CL.

H01L 21/60

TITLE

: BONDING WIRE FOR

SEMICONDUCTOR DEVICE



ABSTRACT :

PURPOSE: To prevent a short circuit and a disconnection even when a deformed loop is touched dy a method wherein the surface of a conductive wire is coated with an insulating material which is melted or evaporated at a temperature of a bonding temperature or higher.

CONSTITUTION: The surface of a metal wire is coated with a material which is provided with an insulating property and which is melted or evaporated at a bonding temperature or higher (350°C or higher). For example, a coating film 1 with which the surface of a conductive wire 2 is coated uniformly has a film thickness of 1µm; the conductive wire 2 of AI is formed by being immersed in a silicone oil and by being dried. Thereby, even when the wire is loosened, no short circuit nor disconnection is caused.

COPYRIGHT: (C)1991, JPO& Japio